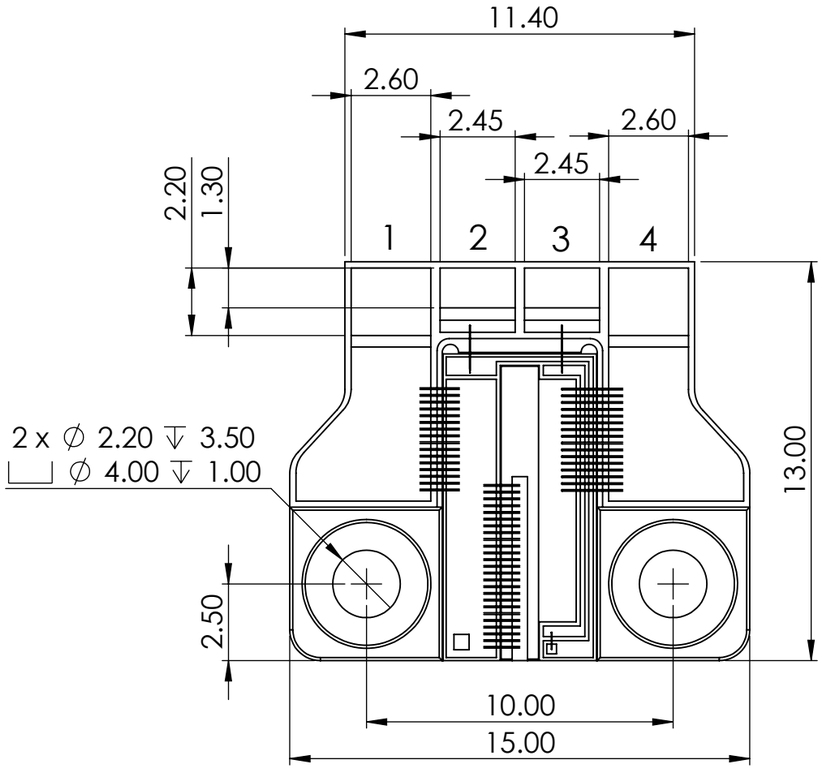
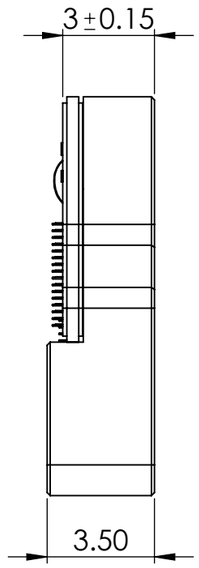
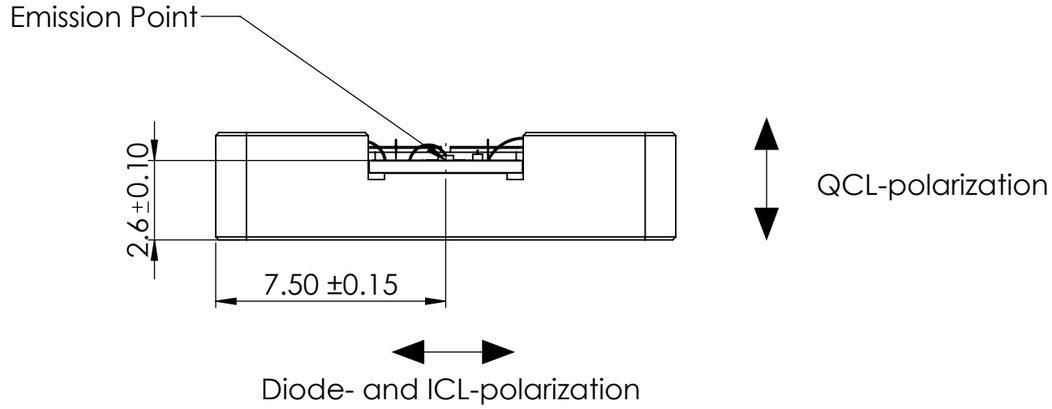
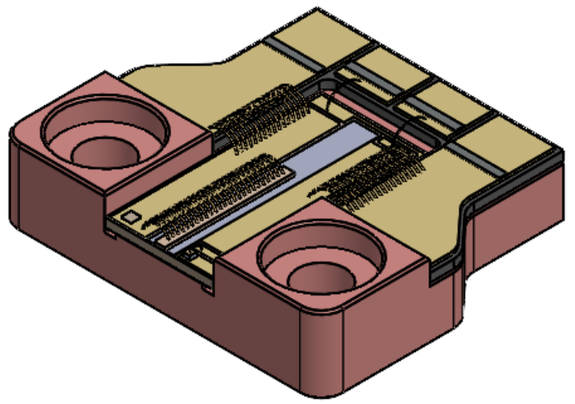




Note: The bottom side of the mount must be connected to a suitable heatsink before operating the laser
Note: The device is not designed for any reverse operation
Note: The device is not designed for use in harsh environments. If in doubt, please contact us
Note: The device must be operated at temperatures above dew point
Note: Use solder only in the PCB-areas behind the solder resist





Diode- and ICL-Pinout:

1: LD -
2: NTC (if installed)
3: NTC (if installed)
4: LD +

QCL-Pinout:

1: LD +
2: NTC (if installed)
3: NTC (if installed)
4: LD -

Material:		**nanoplus Nanosystems and Technologies GmbH** **Oberer Kirschberg 4, 97218 Gerbrunn, Germany** © copyright nanoplus GmbH 2021, all rights reserved nanoplus GmbH reserves the right to modify specifications at any time without notice and is not liable for errors.	Description:
Finish:			Drawn by: WZ / Drawn Date: 25.11.2025
Unless Otherwise Stated: ISO 2768 fK Surface Finish: All Dimensions: **mm**			Checked/Approved by: WZ / Checked/Approved Date: 25.11.2025
Drawing Scale: **5:1**			
Approx Weight: g	Drawing Produced In Accordance With: **BS8888**	Legal Owner:	Part Name:
Projection Method: **THIRD ANGLE**	Sheet Size: **A3**		Drawing Number: / Sheet: / Revision: